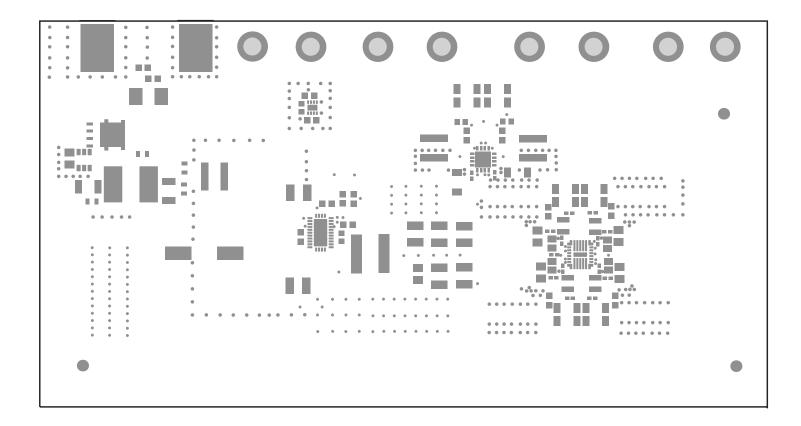
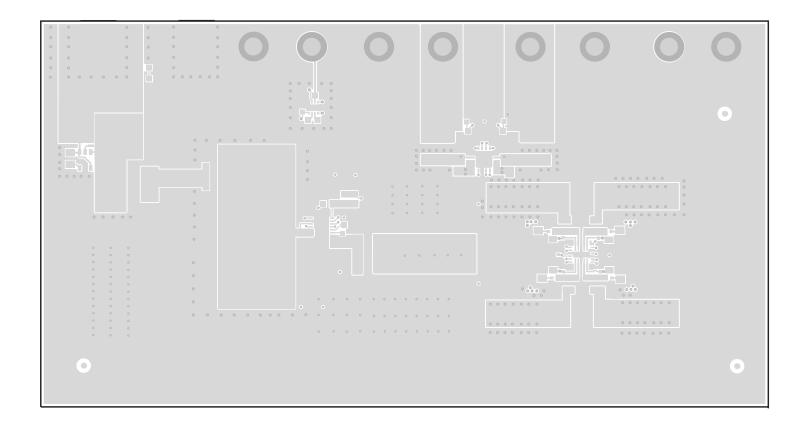


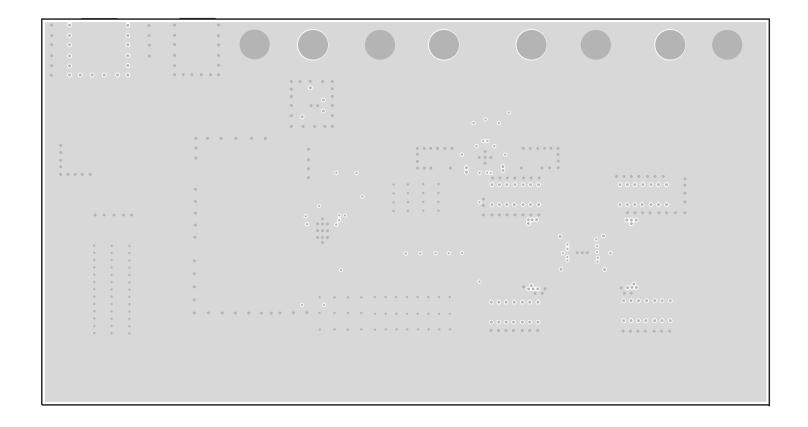
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01492 REV: E1	SVN REV: Not In VersionControl
LAYER NAME = MorpBolanedlaytline	TID #: TIDA-01492	
PLOT NAME = Top Overlay	GENERATED : 11/27/2017 4:04:44	PM TEXAS INSTRUMENTS



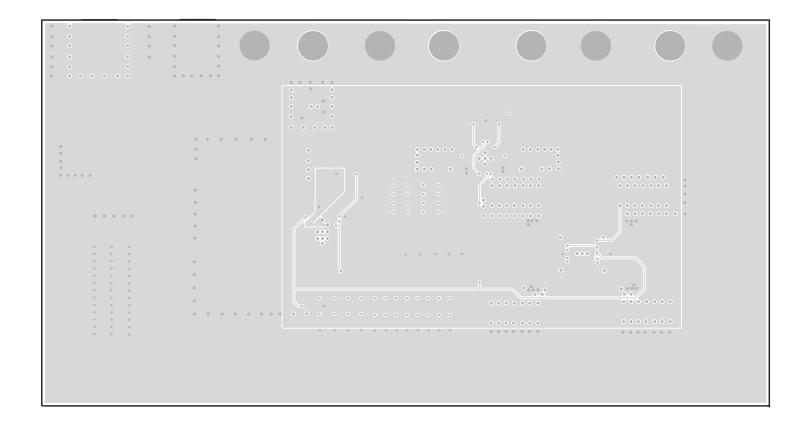
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01492 REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M1 Board Outline	TID #: TIDA-01492	
PLOT NAME = Top Solder Mask	GENERATED : 11/27/2017 4:04:46 P	PM TEXAS INSTRUMENTS



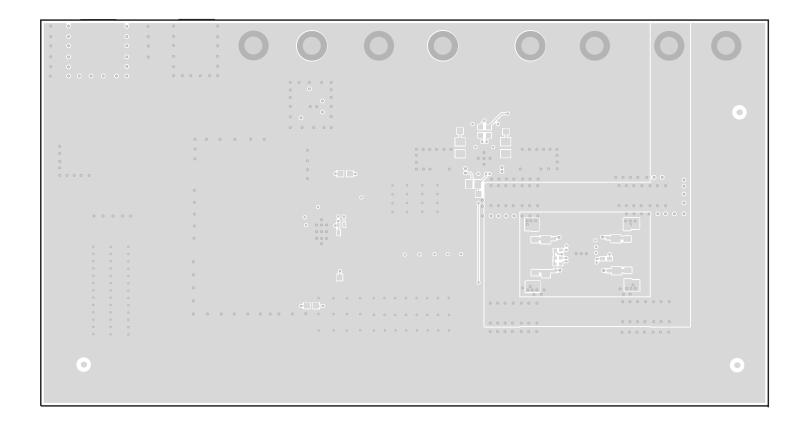
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01492	REV: E1	SVN REV	: Not In VersionControl
LAYER NAME = M1 Board Outline	TID #: TIDA-01492			
PLOT NAME = Top Layer	GENERATED : 11/27/	2017 4: 04: 50	PM	TEXAS INSTRUMENTS



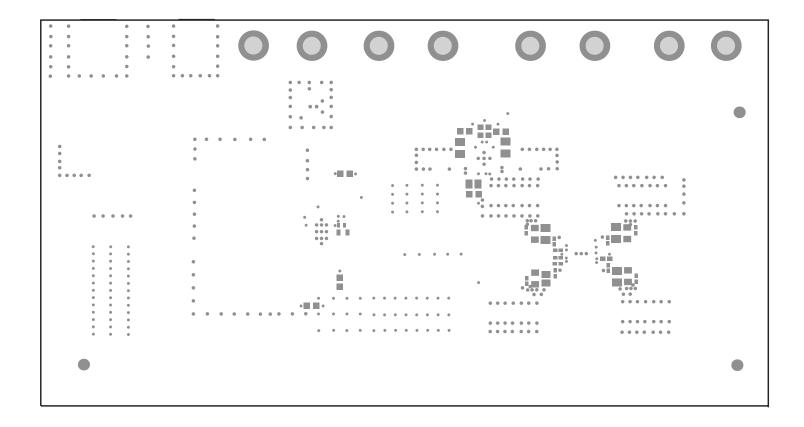
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01492 REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M1 Board Outline	TID #: TIDA-01492	
PLOT NAME = Signal Layer 1	GENERATED : 11/27/2017 4:04:53	PM TEXAS INSTRUMENTS



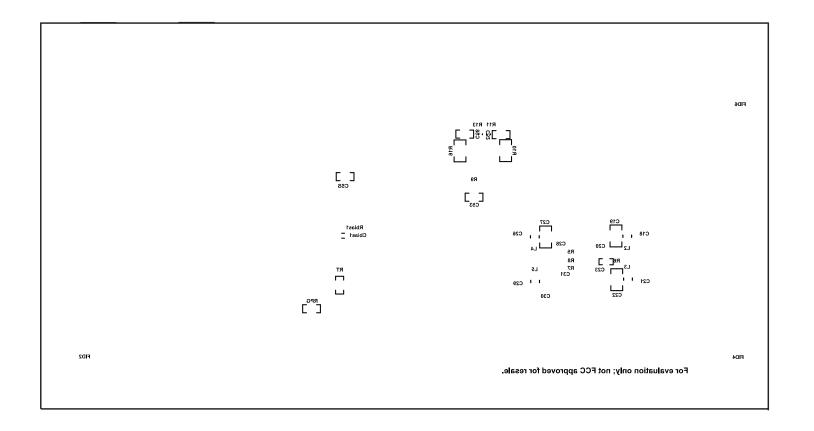
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01492 REV: E1 SVN	REV: Not In VersionControl
LAYER NAME = M1 Board Outline	TID #: TIDA-01492	
PLOT NAME = Signal Layer 2	GENERATED : 11/27/2017 4:04:56 PM	TEXAS INSTRUMENTS



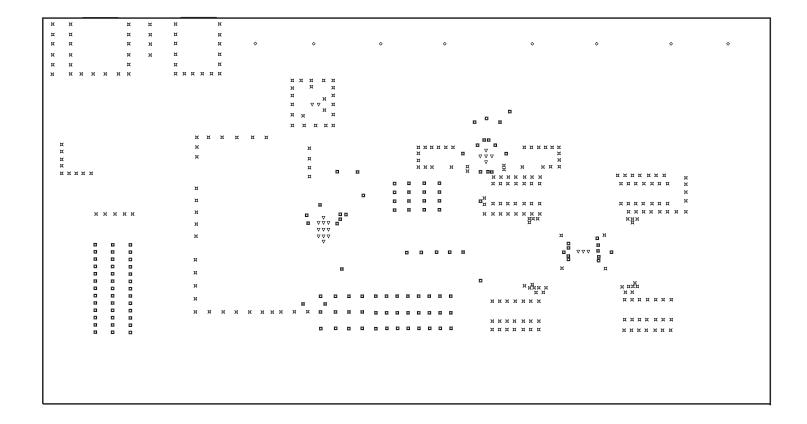
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01492 REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M1 Board Outline	TID #: TIDA-01492	
PLOT NAME = Bottom Layer	GENERATED : 11/27/2017 4:04:59	PM TEXAS INSTRUMENTS



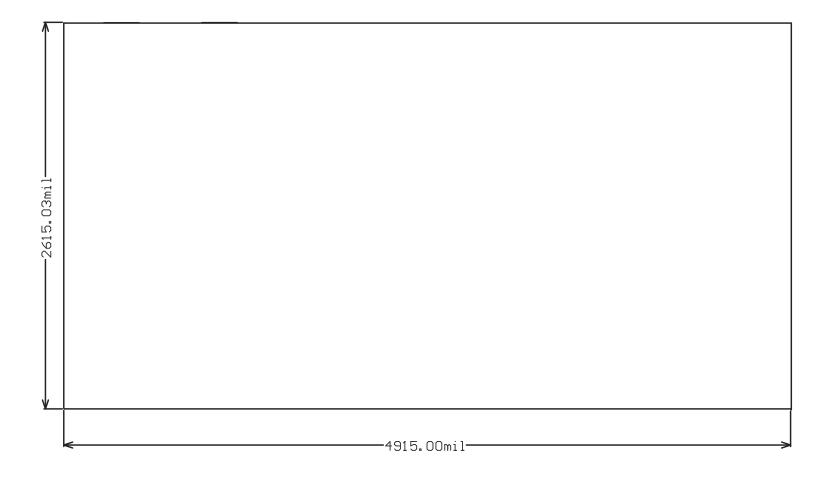
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01492 REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M1 Board Outline	TID #: TIDA-01492	
PLOT NAME = Bottom Solder Mask	GENERATED : 11/27/2017 4:05:03 PM	1 TEXAS INSTRUMENTS

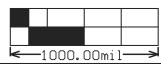


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01492	REV: E1	SVN REV:	Not In VersionControl
LAYER NAME = BibtBomarOlveRultalijne	TID #: TIDA-01492			
PLOT NAME = Bottom Overlay	GENERATED : 11/27/	2017 4: 05: 06	PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01492 REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M1 Board Outline	TID #: TIDA-01492	
PLOT NAME = Drill Drawing	GENERATED : 11/27/2017 4:05:09 PM	1 TEXAS INSTRUMENTS





ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01492 REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M2 Board O umleinnseions	TID #: TIDA-01492	
PLOT NAME = M2 Board Dimensions	GENERATED : 11/27/2017 4:05:16	PM TEXAS INSTRUMENTS

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